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JEDEC STANDARD

Test Method C101

Field-Induced Charged-Device Model Test Method for Electrostatic Discharge Withstand Thresholds of Microelectronic Components

JESD22-C101

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ELECTRONIC INDUSTRIES ASSOCIATION
ENGINEERING DEPARTMENT

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS OF MICROELECTRONIC COMPONENTS

FOREWORD

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IEC-PAS 62162 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:	This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:
Draft PAS	**Report on voting**
47/1462/PAS	47/1495/RVD

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TEST METHOD C101

FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS OF MICROELECTRONIC COMPONENTS

1. PURPOSE

This standard describes a uniform method for establishing charged-device model (CDM) electrostatic discharge (ESD) withstand thresholds.

2. SCOPE

All packaged semiconductor components, thin film circuits, surface acoustic wave (SAW) components, opto-electronic components, hybrid integrated circuits (HICS), and multi-chip modules (MCMs) containing any of these components are to be evaluated according to this standard. The test methods described in this standard may also be used to evaluate components that are shipped as wafers or bare chips. To perform the tests, the components must be assembled into a package similar to that expected in the final application. The package used shall be recorded.

3. REFERENCE DOCUMENT

JEDEC Standard No. 42, “Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices.”